TDC1047

Monolithic Video A/D Converter 7-Bit, 20 Msps

Features

- 7-bit resolution
- 1/2 LSB linearity
- · Sample-and-hold circuit not required
- 20 Msps conversion rate
- · Selectable output format
- Available in 24-pin CERDIP

Applications

- · Low-cost video digitzing
- · Medical imaging
- · TV special effects
- · Video simulators
- · Radar data conversion

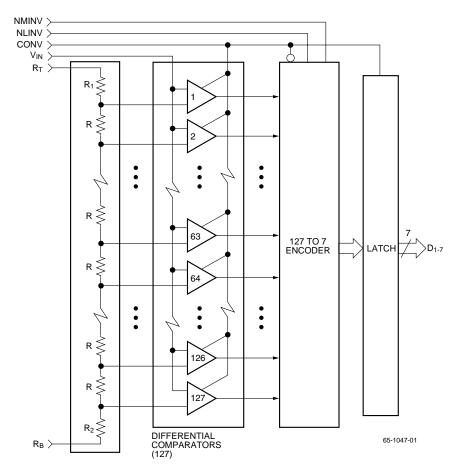
Description

The TDC1047 is a 20 Msps (Megasample per second) full-parallel (flash) analog-to-digital converter, capable of converting an analog signal with full-power frequency components up to 7 MHz into 7-bit digital words. Use of a sample-and-hold circuit is not necessary. All digital inputs and outputs are TTL compatible.

The TDC1047 consists of 127 clocked latching comparators, combining logic, and an output buffer register. A single convert signal controls the conversion operation. The unit can be connected to give either true or inverted outputs in binary or offset two's complement coding.

The TDC1047 is pin and function compatible with the TDC1027, and offers increased performance with lower power dissipation.

Block Diagram



Rev. 1.0.0

Functional Description

General Information

The TDC1047 has three functional sections: a comparator array, encoding logic, and output latches. The comparator array compares the input signal with 127 reference voltages to produce an N-of-127 code (sometimes referred to as a "thermometer" code, as all the comparators referred to voltages more positive than the input signal will be off, and those referred to voltages more negative than the input signal will be on). The encoding logic converts the N-of-127 code into binary or offset two's complement coding, and can invert either output code. This coding function is controlled by DC signals on pins NMINV and NLINV. The output latch holds the output constant between updates.

Power

The TDC1047 operates from two supply voltages, +5.0V and -5.2V. The return for ICC, the current drawn from the +5.0V supply, is DGND. The return for IEE, the current drawn from the -5.2V supply, is AGND. All power and ground pins must be connected.

Reference

The TDC1047 converts analog signals in the range $V_{RB} \le V_{IN} \le V_{RT}$ into digital form. V_{RB} (the voltage applied to the pin at the bottom of the reference resistor chain) and VRT (the voltage applied to the pin at the top of the reference resistor chain) should be between +0.1V and -1.1V. VRT should be more positive than VRB within that range. The voltage applied across the reference resistor chain (V_{RT}–V_{RB}) must be between 0.8V and 1.2V. The nominal voltages are $V_{RT} = 0.00V$ and $V_{RB} = -1.00V$. These voltages may be varied dynamically up to 7MHz. Due to variation in the reference currents with clock and input signals, RT and RB should be low-impedance-to-ground points. For circuits in which the reference is not varied, a bypass capacitor to ground is recommended. If the reference inputs are exercised dynamically as in an Automatic Gain Control (AGC) circuit, a low-impedance reference source is recommended.

Controls

Two function control pins, NMINV and NLINV are provided. These controls are for DC (i.e., steady state) use. They permit the output coding to be either straight binary or offset two's complement, in either true or inverted sense, according to the Output Coding Table. These pins are active LOW as signified by the prefix "N" in the signal name. They may be tied to VCC for a Logic 1 and DGND for a Logic 0.

Convert

The TDC1047 requires a CONVert (CONV) signal. A sample is taken (the comparators are latched) within the Sampling Time Offset (tSTO) of a rising edge on the CONV pin. The 127 to 7 encoding is performed on the falling edge of the CONV signal. The coded result is transferred to the output latches on the next rising edge. The outputs hold the previous data a minimum time (tHO) after the rising edge of the CONV signal. This permits the previous conversion result to be acquired by external circuitry at that rising edge, i.e., data for sample N is acquired by the external circuitry while the TDC1047 is taking input sample N+2.

Analog Input

The TDC1047 uses strobed latching comparators which cause the input impedance to vary with the signal level, as comparator input transistors are cutoff or become active. For optimal performance, both VIN pins must be used and the source impedance of the driving circuit must be less than 30 Ohms. The input signal will not damage the TDC1047 if it remains within the range of VEE to + 0.5V. If the input signal is between the VRT and VRB references, the output will be a binary number between 0 and 127 inclusive. A signal outside this range will indicate either full-scale positive or full-scale negative, depending on whether the signal is off-scale in the positive or negative direction.

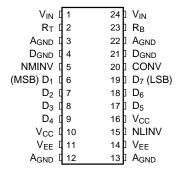
Outputs

The outputs of the TDC1047 are TTL compatible, and capable of driving four low-power Schottky TTL (54/74 LS) unit loads or the equivalent. The outputs hold the previous data a minimum time (tHO) after the rising edge of the CONV signal.

65-1047-02

Pin Assignments

24 Lead Ceramic DIP



Pin Definitions

Pin Name	Pin Number	Value	Pin Function Description
Power			
Vcc	10, 16	+5.0V	Positive Supply Voltage
VEE	11, 14	-5.2V	Negative Supply Voltage
DGND	4, 21	0.0V	Digital Ground
AGND	3, 12, 13, 22	0.0V	Analog Ground
Reference			
RT	2	0.00V	Reference Resistor (Top)
RB	23	-1.00V	Reference Resistor (Bottom)
Controls			
NMINV	5	TTL	Not Most Significant Bit INVert
NLINV	15	TTL	Not Least Significant Bit INVert
Convert			
CONV	20	TTL	Convert
Analog Input			
VIN	1, 24	0V to -1V	Analog Signal Input
Outputs			
D ₁	6	TTL	MSB Output
D ₂ -D ₆	7, 8 , 9, 17, 18	TTL	
D ₇	19	TTL	LSB Output

Absolute Maximum Ratings¹

(beyond which the device will be damaged)

Parameter		Min.	Max.	Unit
Supply Volta	ges			
VCC (measur	red to DGND)	-0.5	+7.0	V
VEE (measur	ed to AGND)	-7.0	+0.5	V
AGND (meas	ured to DGND)	-0.5	+0.5	V
Input Voltage	es	•		
CONV, NMIN	IV, NLINV (measured to DGND)	-0.5	+5.5	V
VIN, VRT, VR	B (measured to AGND)	+0.5	VEE	V
V _{RT} (measur	ed to V _{RB})	-2.2	+2.2	V
Output		•		
Applied volta	ge (measured to DGND) ²	-0.5	5.5	V
Applied curre	nt, externally forced ^{3,4}	-1.0	6.0	mA
Short circuit	duration (single output in high state to ground)		1	sec
Temperature)	•		
Operating	Case	-55	+125	°C
	Junction		+175	°C
Lead, solderi	ng (10 seconds)		+300	°C
Storage		-65	+150	°C

Notes:

- 1. Absolute maximum ratings are limiting values applied individually while all other parameters are within specified operating conditions. Functional operation under any of these conditions is NOT implied.
- 2. Applied voltage must be current limited to specified range.
- 3. Forcing voltage must be limited to specified range.
- 4. Current is specified as positive when flowing into the device.

Operating Conditions

			Temperature Range					
				ď	Extended			
Parameter	rs	Min.	Nom.	Max.	Min.	Nom.	Max.	Units
Vcc	Positive Supply Voltage (measured to DGND)	4.75	5.0	5.25	4.5	5.0	5.5	V
VEE	Negative Supply Voltage (measured to AGND)	-4.9	-5.2	-5.5	-4.9	-5.2	-5.5	V
VAGND	Analog Ground Voltage (measured to DGND)	-0.1	0.0	0.1	-0.1	0.0	0.1	V
tPWL	CONV Pulse Width, (LOW)	14			14			ns
tpwH	CONV Pulse Width, (HIGH)	16			16			ns
VIL	Input Voltage, Logic LOW			0.8			0.8	V
VIH	Input Voltage, Logic HIGH	2.0			2.0			V
loL	Output Current, Logic LOW			4.0			2.0	mA
Іон	Output Current, Logic HIGH			-0.4			-0.4	mA
VRT	Most Positive Reference Input ¹	-0.1	0.0	0.1	-0.1	0.0	0.1	V
VRB	Most Negative Reference Inputs ¹	-0.9	-1.0	-1.1	-0.9	-1.0	-1.1	V
VRT-VRB	Voltage Reference Differential	0.8	1.0	1.2	0.8	1.0	1.2	V
VIN	Input Voltage	VRB		VRT	VRB		VRT	V

Operating Conditions (continued)

			Temperature Range					
		Standard			Extended			
Parameter	rs	Min. Nom. Max. Min. Nom. Max.		Units				
TA	Ambient Temperature, Still Air	0		70				
TC	Case Temperature				-55		125	°C

Note:

DC Electrical Characteristics

			Temperature Range		nge		
			Standard		Exte	nded	
Parameter		Test Conditions	Min.	Max.	Min.	Max.	Units
Icc	Positive Supply Current	V _{CC} = Max, static ¹		25		30	mA
IEE	Negative Supply Current	VEE = Max, static ¹					
		T _A = 0°C to 70°C		-170			mA
		TA = 70°C		-135			mA
		T _C = -55°C to 125°C				-220	mA
		T _C = 125°C				-130	mA
IREF	Reference Current	VRT, VRB = Nom		35		50	mA
RREF	Total Reference Resistance		28		20		Ω
RIN	Input Equivalent Resistance	VRT, VRB = Nom, VIN = VRB	100		40		ΚΩ
CIN	Input Capacitance			60		60	pF
ICB	Input Constant Bias Current	VEE = Max		150		300	μА
IIL	Input Current, Logic LOW	VCC = Max, V _I = 0.5V			•	•	
		CONV		-0.4		-0.6	mA
		NMINV, NLINV		-0.6		-0.8	mA
lін	Input Current, Logic HIGH	VCC = Max, VI = 2.4V		50		50	μА
l _l	Input Current, Max Input Voltage	VCC = Max, V _I = 5.5V		1.0		1.0	mA
VOL	Output Voltage, Logic LOW	VCC = Min, IOL = Max		0.5		0.5	V
Vон	Output Voltage, Logic HIGH	VCC = Min, IOH = Max	2.4		2.4		V
los	Short Circuit Output Current	VCC = MAX, One pin to ground, one second duration.		-30		-30	mA
Сі	Digital Input Capacitance	TA = 25°C, F = 1MHz		15		15	pF

Note:

^{1.} VRT must be more positive than VRB, and voltage reference differential must be within specified range.

^{1.} Worst case, all digital inputs and outputs LOW.

AC Electrical Characteristics

			Temperature Range				
			Standard		Extende		
Parameter		Test Conditions	Min. Max.		Min.	Max.	Units
Fs	Maximum Conversion Rate	VCC = Min, VEE = Min	20		20		MSPS
tsto	Sampling Time Offset	VCC = Min, VEE = Min		7		10	ns
tD	Output Delay	VCC = Min, VEE = Min, Load 1		30		35	ns
tHO	Output Hold Time	VCC = MAX, VEE = Max, Load 1	5		5		ns

Timing Diagram

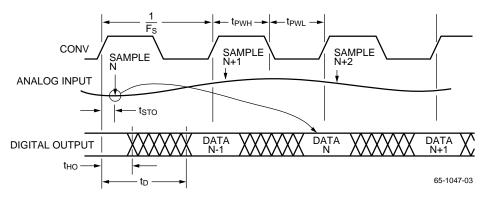


Figure 1. Timing Diagram

System Performance Characteristics

			Tei	Temperature		nge	
			Stan	Standard		nded	
Paran	neter	Test Conditions	Min.	Max.	Min.	Max.	Units
ELI	Linearity Error Integral, Independent	VRT, VRB = Nom		0.4		0.4	%
ELD	Linearity Error Differential			0.4		0.4	%
CS	Code Size	VRT, VRB = Nom	30	170	30	170	% Nominal
Vот	Offset Voltage Top	VIN = VRT		+50		+50	mV
Еов	Offset Voltage Bottom	VIN = VRB		-30		-30	mV
Tco	Temperature Coefficient			±20		±20	μV/°C
BW	Bandwidth, Full Power Input		7		7		MHz
tTR	Transient Response, Full-Scale			10		10	ns
SNR	Signal-to-Noise Ratio	7MHz Bandwidth, 20M	Isps Co	nversio	n		
	Peak Signal/RMS Noise	1 MHz Input	48		46		dB
		7 MHz Input	46		44		dB
	RMS Signal/RMS Noise	1 MHz Input	39		37		dB
		7 MHz Input	37		35		dB
EAP	Aperture Error			50		50	ps
DP	Differential Phase Error ¹	F _S = 4 x NTSC		1.5		1.5	Degree
DG	Differential Gain Error ¹	Fs = 4 x NTSC		2.5		2.5	%

Note:

^{1.} In Excess of quantization.

Equivalent Circuits

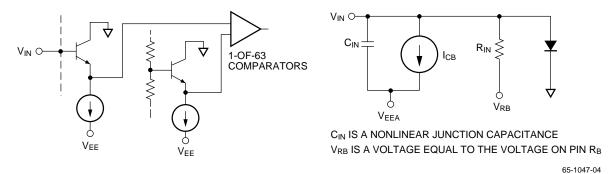


Figure 2. Simplified Analog Input Equivalent Circuit

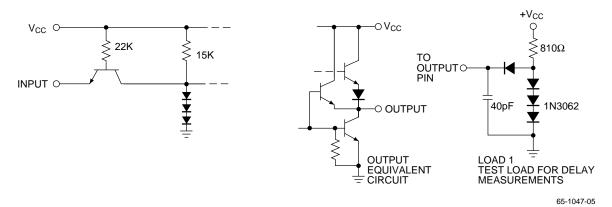


Figure 3. Digital Input Equivalent Circuit

Figure 4. Output Circuits

Output Coding Table

		Bir	nary	Two's Co	mplement
	Range	True	Inverted	True	Inverted
Step	-1.0000V FS 7.874mV STEP	NMINV=1 NLINV=1	0	0 1	1 0
000	0.0000V	0000000	1111111	1000000	0111111
001	-0.0078V	0000001	1111110	1000001	0111110
•	•	•	•	•	•
•	•	•	•	•	•
•	•	•	•	•	•
063	-0.4960V	0111111	1000000	1111111	0000000
064	-0.5039V	1000000	0111111	0000000	1111111
•	•	•	•	•	•
•	•	•	•	•	•
•	•	•	•	•	•
126	-1.9921V	1111110	0000001	0111110	1000001
127	-1.0000V	1111111	0000000	0111111	1000000

Note:

^{1.} Voltages are code midpoints when calibrated (see Calibration Section).

Applications Discussion

Calibration

To calibrate the TDC1047, adjust V_{RT} and V_{RB} to set the 1st and 127th thresholds to the desired voltages in the block diagram. Note that R_1 is greater than R, ensuring calibration with a positive voltage on R_T . Assuming a 0V to -1V desired range, continuously strobe the converter with -0.0039V on

the analog input, and adjust VRT for output toggling between codes 00 and 01. Then apply -0.9961V and adjust VRB for toggling between codes 126 and 127. Instead of adjusting VRT, RT can be connected to analog ground and the 0V end of the range calibrated with a buffer offset control. RB is a convenient point for gain adjust that is not in the analog signal path. These techniques are employed in Figure 5

Typical Interface Circuit

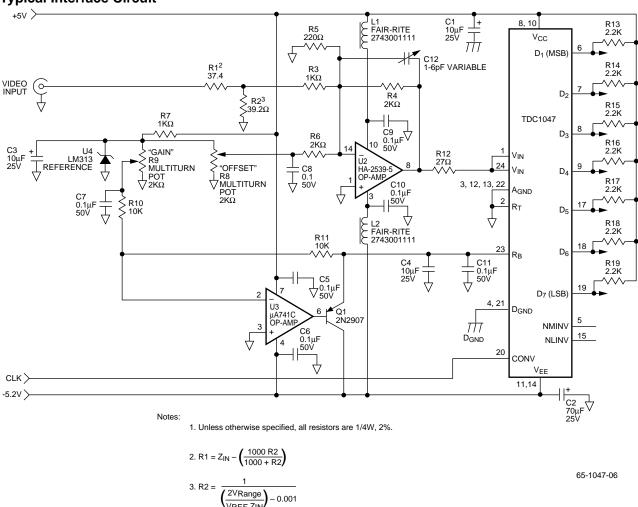


Figure 5. Typical Interface Circuit

Notes:

Notes:

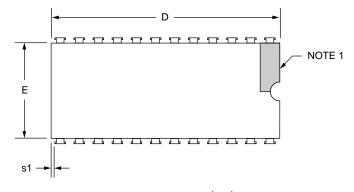
Mechanical Dimensions

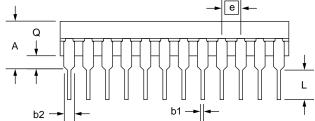
24 Lead Ceramic DIP

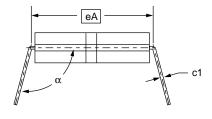
Cumbal	Inches		Millim	Notes	
Symbol	Min.	Max.	Min.	Max.	Notes
Α	_	.225	_	5.72	
b1	.014	.023	.36	.58	8
b2	.045	.065	1.14	1.65	2, 8
c1	.008	.015	.20	.38	8
D	_	1.290	_	32.77	4
Е	.500	.610	12.70	15.49	4
е	.100	BSC	2.54	BSC	5, 9
eA	.600	BSC	15.24	BSC	7
L	.120	.200	3.05	5.08	
Q	.015	.075	.38	1.91	3
s1	.005	_	.13	_	6
α	90°	105°	90°	105°	

Notes:

- Index area: a notch or a pin one identification mark shall be located adjacent to pin one. The manufacturer's identification shall not be used as pin one identification mark.
- 2. The minimum limit for dimension "b2" may be .023 (.58mm) for leads number 1, 12, 13 and 24 only.
- 3. Dimension "Q" shall be measured from the seating plane to the base plane.
- 4. This dimension allows for off-center lid, meniscus and glass overrun.
- 5. The basic pin spacing is .100 (2.54mm) between centerlines. Each pin centerline shall be located within \pm .010 (.25mm) of its exact longitudinal position relative to pins 1 and 24.
- 6. Applies to all four corners (leads number 1, 12, 13, and 24).
- 7. "eA" shall be measured at the center of the lead bends or at the centerline of the leads when " α " is 90°.
- All leads Increase maximum limit by .003 (.08mm) measured at the center of the flat, when lead finish applied.
- 9. Twenty-two spaces.







Ordering Information

Product Number	Temperature Range	Screening	Package	Package Marking
TDC1047B7C	STD-T _A = 0°C to 70°C	Commercial	24 Lead Ceramic DIP	1047B7C
TDC1047B7V	EXT-T _C = -55°C to 125°C	MIL-STD-883	24 Lead Ceramic DIP	1047B7V

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